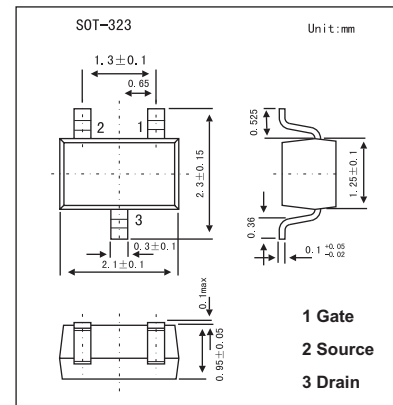
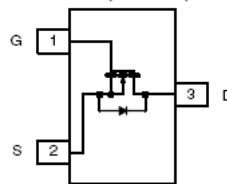


N-Channel 30-V (D-S) MOSFET

KI1304BDL

■ Features

- TrenchFET Power MOSFET
- 100% Rg Tested

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Drain-source voltage	V_{DS}	30	V
Gate-source voltage	V_{GS}	± 12	V
Continuous drain current ($T_J = 150^\circ\text{C}$) $T_c=25^\circ\text{C}$ $T_c=70^\circ\text{C}$	I_D	0.90 0.71	A
Continuous drain current ($T_J = 150^\circ\text{C}$) $T_a=25^\circ\text{C}$ $T_a=70^\circ\text{C}$	I_D	0.85*1,2 0.68*1,2	A
Pulsed drain current	I_{DM}	4	A
Continuous Source Drain Diode Current $T_c=25^\circ\text{C}$ $T_a=25^\circ\text{C}$	I_S	0.31 0.28	A
Power dissipation $T_c=25^\circ\text{C}$ $T_c=70^\circ\text{C}$	P_D	0.37 0.24	W
Power dissipation $T_a=25^\circ\text{C}$ $T_a=70^\circ\text{C}$	P_D	0.34*1,2 0.22*1,2	W
Operating junction and storage temperature range	T_J, T_{stg}	-55 to +150	$^\circ\text{C}$

*1 Surface Mounted on 1" X 1" FR4 Board.

*2 $t = 5$ sec

■ Thermal Resistance Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient*1,2 $t \leq 5$ sec	R_{thJA}	315	375	$^\circ\text{C}/\text{W}$
Maximum Junction-to-Foot (Drain) Steady State	R_{thJF}	285	340	

*1 Surface Mounted on 1" X 1" FR4 Board.

*2 Maximum under steady state conditions is $360^\circ\text{C}/\text{W}$.

KI1304BDL

■ Electrical Characteristics Ta = 25℃

Parameter	Symbol	Testconditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = 250 μ A	30			V
V _{DS} Temperature Coefficient	ΔV _{DS} /T _J	I _D = 250 μ A		27.3		mV/℃
V _{GS(th)} Temperature Coefficient	ΔV _{GS(th)} /T _J			3		
Gate threshold voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μ A	0.6		1.3	V
Gate-body leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ± 12 V			± 100	nA
Zero gate voltage drain current	I _{DSS}	V _{DS} = 30 V, V _{GS} = 0 V			1	μ A
		V _{DS} = 30 V, V _{GS} = 0 V, T _J = 70 ℃			5	
On-state drain current	I _{D(on)}	V _{DS} ≥ 5 V, V _{GS} = 4.5 V	4			A
Drain-source on-state resistance	r _{DS(on)}	V _{GS} = 4.5 V, I _D = 0.9		0.216	0.270	Ω
		V _{GS} = 2.5V, I _D = 0.75		0.308	0.385	
Forward transconductance	g _{fs}	V _{DS} = 15 V, I _D = 0.9		2		S
Input Capacitance	C _{iss}	V _{DS} = 15 V, V _{GS} = 0 V, f = 1 MHz		100		pF
Output Capacitance	C _{oss}			30		
Reverse Transfer Capacitance	C _{rss}			20		
Total gate charge *	Q _g	V _{DS} = 15V, V _{GS} = 4.5 V, I _D = 0.9		1.8	2.7	nC
Total gate charge *	Q _g			1.1	1.7	
Gate-source charge *	Q _{gs}			0.4		
Gate-drain charge *	Q _{gd}			0.6		
Gate Resistance	R _g	f = 1MHz		1.5	2.3	Ω
Turn-on time	t _{d(on)}	V _{DD} = 15V, R _L = 22 Ω, I _D = 0.68A, V _{GEN} = 4.5V, R _G = 1 Ω		10	15	ns
	t _r			30	45	
Turn-off time	t _{d(off)}			5	25	
	t _r			10	15	
Continuous Source-Drain Diode Current	I _S	TC = 25℃			0.31	A
Pulse Diode Forward Current*	I _{SM}				4	
Body Diode Voltage	V _{SD}	I _S = 0.28 A		0.8	1.2	V
Body Diode Reverse Recovery Time	t _{rr}	I _F = 0.28A, dI/dt = 100A/μ s, T _J = 25℃		50	75	ns
Body Diode Reverse Recovery Charge	Q _{rr}			105	160	nC
Reverse Recovery Fall Time	t _a			34		ns
Reverse Recovery Rise Time	t _b			16		ns

* Pulse test: PW ≤ 300 μs duty cycle ≤ 2%.

■ Marking

Marking	KF
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